

GLSVLSI 2017

Banff, Alberta, Canada, May 10-12, 2017

<http://www.glsvlsi.org/>

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The 27th edition of GLSVLSI will be held in the beautiful Canadian Rockies. Original, unpublished papers describing research in the general areas of VLSI and hardware design are solicited. Please visit <http://www.glsvlsi.org/> for more information.

In addition to the traditional topic areas of GLSVLSI listed below, papers are solicited for a special theme of “**Green Technologies for Computing and IoT Applications.**”

Program Tracks:

- **VLSI Design:** ASIC and FPGA design, microprocessors/micro-architectures, embedded processors, analog/digital/mixed-signal systems, NoC, SoC, IoT, interconnects, memories.
- **VLSI Circuits and Power Aware Design:** analog/digital/mixed-signal circuits, RF and communication circuits, chaos/neural/fuzzy-logic circuits, high-speed/low-power circuits, temperature estimation/optimization, power estimation/optimization.
- **Computer-Aided Design (CAD):** hardware/software co-design, high-level synthesis, logic synthesis, simulation and formal verification, layout, design for manufacturing, algorithms and complexity analysis.
- **Testing, Reliability, Fault-Tolerance:** digital/analog/mixed-signal testing, reliability, robustness, static and dynamic defect- and fault-recoverability, variation-aware design.
- **Emerging Computing & Post-CMOS Technologies:** nanotechnology, molecular and quantum computing, approximate and stochastic computing, sensor and sensor networks, post CMOS VLSI.
- **Hardware Security:** trusted IC, IP protection, hardware security primitives, reverse engineering, hardware Trojan, side-channel analysis, CPS and IoT security.
- **Biochips and Biological Systems:** bio-inspired and neuromorphic circuits and systems, BioMEMs, lab-on-a-chip, biosensors, hardware and software solutions for medical diagnostics, CAD tools for biology and biomedical systems, implantable and wearable devices, systems and synthetic biology.

Paper submission deadline:

December 23, 2016

Acceptance Notification:

February 13, 2017

Camera-Ready Paper Due:

March 13, 2017

Paper Submission: Authors are invited to submit full-length (6 pages maximum), original, unpublished papers along with an abstract of at most 200 words. To enable blind review, the author list should be omitted from the main document. Previously published papers or papers currently under review for other conferences/journals should NOT be submitted and will not be considered. Electronic submission in PDF format to the <http://www.glsvlsi.org> website is required. Author and contact information (name, affiliation, mailing address, telephone, fax, e-mail) must be entered during the submission process.

Paper Format: Submissions should be in camera-ready two-column format, following the ACM proceedings specifications located at:

<http://www.acm.org/sigs/pubs/proceed/template.html>

and the classification system detailed at: <http://www.acm.org/class/1998>

Paper Publication and Presenter Registration: Papers will be accepted for regular or poster presentation at the symposium. Every accepted paper MUST have at least one author registered to the symposium by the time the camera-ready paper is submitted; at least one of the authors is also expected to attend the symposium and present the paper.

